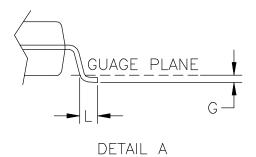


L	ΓR	MIN	MAX			
Α	IN. MM	_ _	.104 2.64			
A1	IN. MM	.004 .102	_ _			
A2	IN. MM	.082 2.08	.094 2.39			
b	IN. MM	.014 0.36	.020 0.51			
С	IN. MM	.006 0.15	.013 0.33			
D	IN. MM	.810 20.57	.824 20.93			
е	IN. MM	.050 1.27	BSC BSC			
E1	IN. MM	.292 7.42	.299 7.59			
I	IN. MM	.405 10.29	.419 10.64			
L	IN. MM	.021 0.53	.041 1.04			
G	IN. MM	.014 0.36	BSC BSC			



NOTES:

A TERMINAL 1 IDENTIFIER MUST BE POSITIONED SO THAT 1/2 OR MORE OF IT'S AREA IS CONTAINED IN THE HATCHED ZONE.

2 "D" AND "E1" DIMENSIONS DO NOT INCLUDE MOLD FLASH OR PROTRUSIONS, BUT DOES INCLUDE MOLD MISMATCH AND ARE MEASURED AT THE MOLD PARTING LINE. MOLD FLASH OR PROTRUSIONS SHALL NOT EXCEED .003 INCHES PER SIDE.

DIMENSION "b" IS MEASURED BELOW THE LOWER RADIUS OF THE FOOT.

SIGNATURE	DATE		11		allas					
DOC. CONTROL: Semiconductor										
ENGR. MGP:		MARKETING OUTLINE— .300" SOIC 32 LEAD .050" PITCH								
MFG. ENGR:										
CHECKED BY:		SIZE	FSCM NO		PART NO.				REV	
DRAWN BY:		Α							А	
DO NOT SCALE DWG.		SCALE	N/A			SHEET	1	OF	1	